Technical Data Sheet

LOCTITE ABLESTIK 8387A

October 2014

PRODUCT DESCRIPTION

LOCTITE ABLESTIK 8387A provides the following product characteristics:

Technology	Epoxy
Appearance	blue
Cure	Heat cure
Product Benefits	• Non-conductive • Low temperature cure • Fast cure capability • Long work life
Application	Die attach
Typical Package Application	Smart Card

LOCTITE ABLESTIK 8387A die attach adhesive is designed for high throughput smart card bonding applications.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Thixotropic Index (0.5/5 rpm)	≥4.9
Viscosity, Brookfield CP51, 25 °C, mPa·s (cP):	
Speed 5 rpm	9,000
Work Life @ 25°C, hours	72
Storage Life (from date of manufacture):	
@ -20ºC, days	183
@ -40ºC, days	365

TYPICAL CURING PERFORMANCE

Cure Schedule

2 minutes @ 150°C

Alternate Cure Schedule

15minutes @ 125°C

Weight Loss on Cure

10 x 10 mm Si die on glass slide, %	1

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties :

Glass Transition Temperature, TMA penetration mode, °C	77
Extractable Ionic Content, ppm:	
Chloride (Cl-) Sample cured 15 min @ 125ºC	≤150
Sodium (Na+)	≤10
Potassium (K+)	≤15

Tensile Modulus, DMTA :		
@ -65 °C	N/mm² (psi)	2,500 (360,000)
@ 25 °C	N/mm² (psi)	1,400 (201,000)
@ 150 °C	N/mm² (psi)	43 (6,000)
@ 200 °C	N/mm² (psi)	43 (6,000)

TYPICAL PERFORMANCE OF CURED MATERIAL

Die Shear Strength:	
@ 25ºC, kg-f/die:	
3 X 3 mm (120 x 120 mil) Si die on Ag/Cu LF	30
3 X 3 mm (120 x 120 mil) Si die on Cu LF	28
2 X 2 mm (80 x 80 mil) Si die on T2 FR4 LF	11
@ 250ºC, kg-f/die:	
12.7 X 12.7 mm (500 x 500 mil) Si die on Cu LF	29
Chip Warpage @ 25ºC, µm	35

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

THAWING:

1. Allow container to reach room temperature before use.
2. After removing from the freezer, set the syringes to stand vertically while thawing.
3. DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
4. DO NOT re-freeze. Once thawed to -40°C, the adhesive should not be re-frozen.

DIRECTIONS FOR USE

1. LOCTITE ABLESTIK 8387A adhesive is designed for pin transfer, dot dispensing or syringe dispensing.
2. Dispense the desired amount of material and place die into deposit using downward force to achieve desired bondline.
3. Adhesive must be completely used within the product's recommended work life.

Not for product specifications
The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

Storage
Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage : -40 to -20 °C

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions
(°C x 1.8) + 32 = °F
kV/mm x 25.4 = V/mil
mm / 25.4 = inches
N x 0.225 = lb
N/mm x 5.71 = lb/in
N/mm² x 145 = psi
MPa = N/mm²
MPa x 145 = psi
N·m x 8.851 = lb·in
N·m x 0.738 = lb·ft
N·mm x 0.142 = oz·in
mPa·s = cP

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